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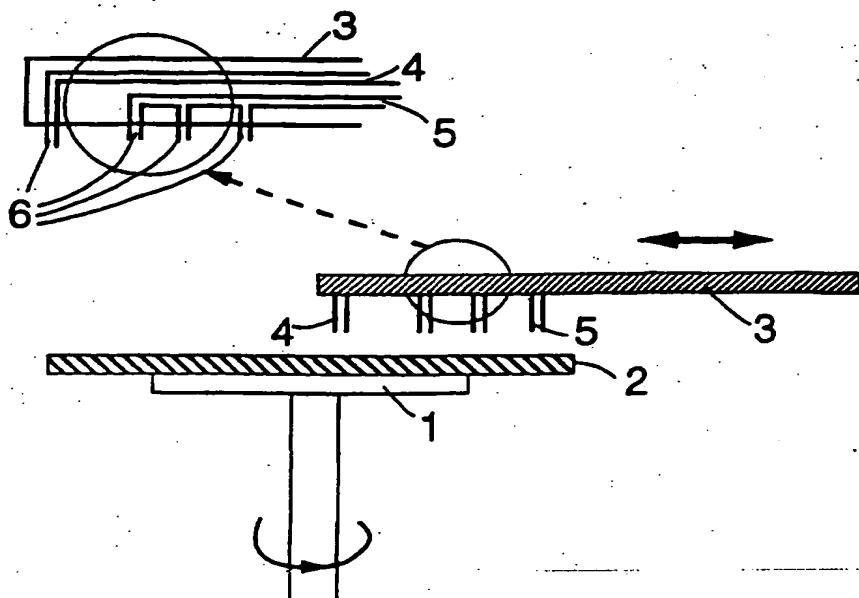
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### (54) Method of removing a liquid from a surface of a rotating substrate

(57) A method of removing a liquid, i.e. a wet processing liquid, from a surface of at least one substrate is disclosed. A liquid is supplied on a surface of substrate. Simultaneously or thereafter besides the liquid also a gaseous substance can be supplied thereby creating at least locally a sharply defined liquid-vapour boundary. The gaseous substance and the liquid can be

selected such that the gaseous substance is miscible with the liquid and when mixed with the liquid yields a mixture having a surface tension lower than that of the liquid. According to the invention, the substrate is subjected to a rotary movement at a speed to guide said liquid-vapour boundary over said substrate thereby removing said liquid from said substrate.

Figure 1



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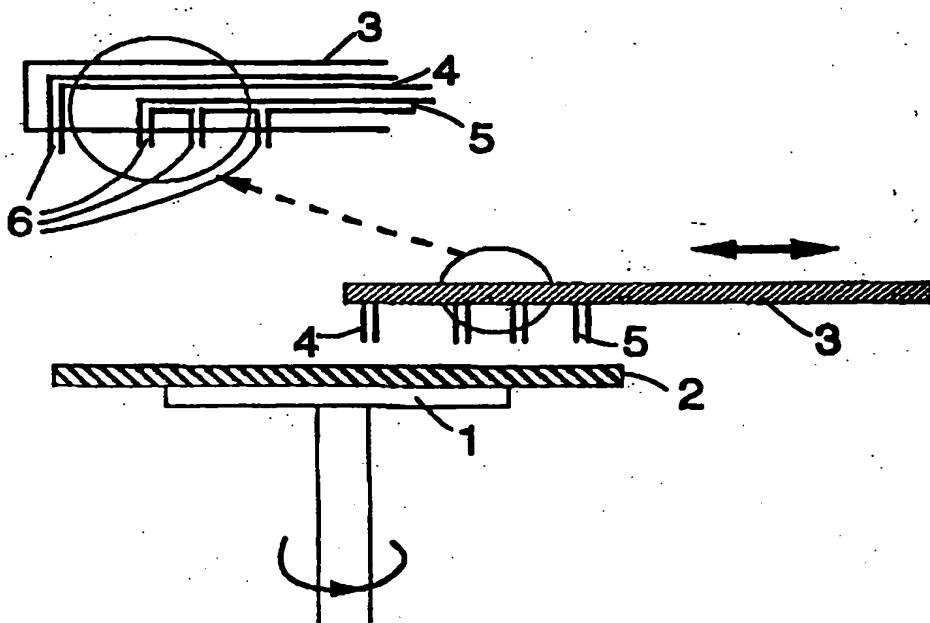
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(54) Title: METHOD AND APPARATUS FOR REMOVING A LIQUID FROM A SURFACE



(57) Abstract

A method and an apparatus for removing a liquid, i.e. a wet processing liquid, from at least one surface of at least one substrate is disclosed. A liquid is supplied on a surface of substrate. Simultaneously or thereafter the liquid or the substrate is locally heated to thereby reduce the surface tension of said liquid. By doing so, at least locally a sharply-defined-liquid-ambient boundary is created. According to the invention, the substrate is subjected to a rotary movement at a speed to guide said liquid-ambient boundary over the surface of the substrate thereby removing said liquid from said surface.

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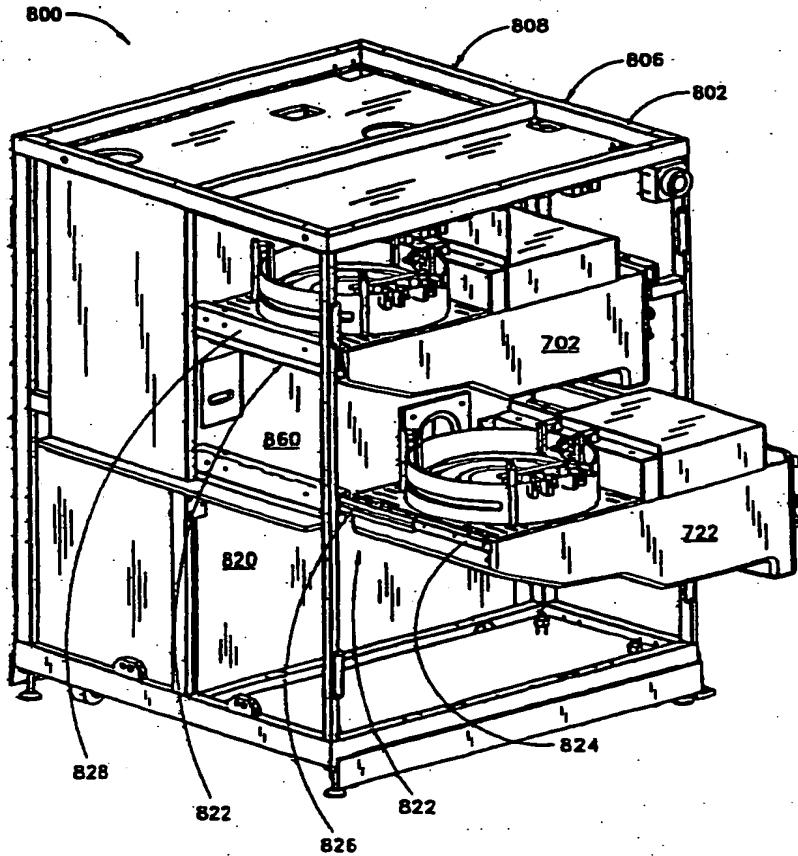
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(54) Title: MEGASONIC CLEANER AND DRYER SYSTEM



(57) Abstract: An apparatus for drying a generally flat substrate (114) that has been cleaned has a rotatable support (110) for supporting the substrate (114), a substrate drying assembly (120), and a controller (147). The substrate drying assembly (120) includes a substrate drying assembly support arm (130), an outlet for applying liquid to an upper surface of the substrate (114), and an outlet for applying a drying vapor to the upper surface of the substrate (114). The substrate drying assembly (120) is configured to position the liquid applying outlet and to position the vapor applying outlet above a portion of the substrate (114). The controller (147) causes the substrate drying assembly (120) to be retracted over the upper surface of the substrate (114) at a faster rate near a center of the substrate (114) than near a periphery of the substrate (114).